

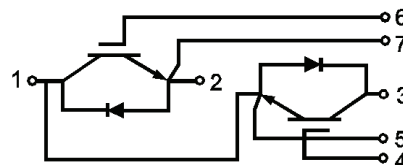


GT200HF120T2VH

IGBT Module

Features:

- Field Stop Trench Gate IGBT
- Short Circuit Rated >10 μ s
- Low Saturation Voltage
- Low Switching Loss
- 100% RBSOA Tested(2 \times I_c)
- Low Stray Inductance
- Lead Free, Compliant with RoHS Requirement



Applications:

- Welding
- HEV Inverter
- Industrial Motor Drives
- UPS

Maximum Rated Values of IGBT (T_C=25°C unless otherwise specified)

V _{CES}	Collector-Emitter Blocking Voltage		1200	V
V _{GES}	Gate-Emitter Voltage		±20	V
I _C	Continuous Collector Current	T _C =80°C	200	A
		T _C =25°C	400	A
I _{CM}	Repetitive Peak Collector Current	T _J =150°C	400	A
t _{sc}	Short Circuit Withstand Time		>10	μs
P _D	Maximum Power Dissipation per leg	T _C =25°C T _{Jmax} =150°C	1202	W



Electrical Characteristics of IGBT ($T_C=25^\circ\text{C}$ unless otherwise specified)

Static Characteristics

Symbol	Description	Conditions	Min.	Typ.	Max.	Units
$V_{GE(th)}$	Gate-Emitter Threshold Voltage	$I_C=3\text{mA}$, $V_{CE}=V_{GE}$	5.0	5.7	6.7	V
$V_{CE(sat)}$	Collector-Emitter Saturation Voltage	$I_C=200\text{A}$, $V_{GE}=15\text{V}$	$T_J=25^\circ\text{C}$	2.20		V
			$T_J=125^\circ\text{C}$	2.90		V
			$T_J=150^\circ\text{C}$	3.10		V
I_{CES}	Collector-Emitter Leakage Current	$V_{GE}=0\text{V}$, $V_{CE}=V_{CES}$, $T_J=25^\circ\text{C}$			1	mA
I_{GES}	Gate-Emitter Leakage Current	$V_{GE}=\pm 20\text{V}$, $V_{CE}=0\text{V}$, $T_J=25^\circ\text{C}$			400	nA
C_{ies}	Input Capacitance	$V_{CE}=25\text{V}$, $V_{GE}=0\text{V}$, $f=100\text{kHz}$		17.27		nF
C_{oes}	Output Capacitance			1.16		nF
C_{res}	Reverse Transfer Capacitance			0.52		nF

Switching Characteristics

$t_{d(on)}$	Turn-on Delay Time	$V_{CC}=600\text{V}$, $I_C=200\text{A}$, $R_{Gon}=4.7\Omega$, $V_{GE}=\pm 15\text{V}$, Inductive Load	$T_J=25^\circ\text{C}$	270		ns
			$T_J=125^\circ\text{C}$	282		
			$T_J=150^\circ\text{C}$	269		
t_r	Rise Time		$T_J=25^\circ\text{C}$	99		ns
			$T_J=125^\circ\text{C}$	110		
			$T_J=150^\circ\text{C}$	115		
$t_{d(off)}$	Turn-off Delay Time		$T_J=25^\circ\text{C}$	192		ns
			$T_J=125^\circ\text{C}$	202		
			$T_J=150^\circ\text{C}$	195		
t_f	Fall Time	$T_J=25^\circ\text{C}$	134		ns	
		$T_J=125^\circ\text{C}$	156			
		$T_J=150^\circ\text{C}$	160			
E_{on}	Turn-on Switching Loss	$V_{CC}=600\text{V}$, $I_C=200\text{A}$, $R_{Gon}=4.7\Omega$, $V_{GE}=\pm 15\text{V}$, $di/dt=1495\text{A}/\mu\text{s}$ ($T_J=150^\circ\text{C}$), Inductive Load	$T_J=25^\circ\text{C}$	13.2		mJ
			$T_J=125^\circ\text{C}$	21.9		
			$T_J=150^\circ\text{C}$	27.5		



E _{off}	Turn-off Switching Loss	V _{CC} =600V, I _C =200A, R _{Goff} =4.7Ω, V _{GE} =±15V, du/dt=8094V/μs (T _J =150°C), Inductive Load	T _J =25°C	8.0	mJ
			T _J =125°C	11.2	
			T _J =150°C	13.1	
Q _g	Total Gate Charge	V _{GE} =+15V...-15V	T _J =25°C	0.81	μC
R _{g internal}	Internal Gate Resistance		T _J =25°C	1.5	Ω
RBSOA	I _C =400A, V _{CC} =1050V, V _p =1200V, R _{Goff} =4.7Ω, V _{GE} =+15V to 0V, T _J =150°C			Trapezoid	
I _{SC}	V _{CC} =600V, V _{GE} =±15V, R _{Gon} =4.7Ω, R _{Goff} =4.7Ω, t _p =10us, T _J =125°C			694	A
R _{θJC}	IGBT Thermal Resistance: Junction-to-Case (per IGBT)			0.104	°C/W

Maximum Rated Values of Diode (T_C=25°C unless otherwise specified)

V _{RRM}	Repetitive Peak Reverse Voltage	1200	V
I _F	Diode Continuous Forward Current	200	A
I _{FM}	Diode Maximum Forward Current	400	A

Electrical Characteristics of Diode (T_C=25°C unless otherwise specified)

Symbol	Description	Conditions	Min.	Typ.	Max.	Units
V _{FM}	Forward Voltage	I _F =200A	T _J =25°C	2.35		V
			T _J =125°C	2.45		
			T _J =150°C	2.40		
t _{rr}	Reverse Recovery Time		T _J =25°C	154		ns
			T _J =125°C	342		
			T _J =150°C	375		
I _{rr}	Peak Reverse Recovery Current	I _F =200A, -di _F /dt=1875A/μs (T _J =150°C), V _R =600V, V _{GE} =-15V	T _J =25°C	91		A
			T _J =125°C	131		
			T _J =150°C	128		
Q _{rr}	Reverse Recovery Charge		T _J =25°C	8.29		μC
			T _J =125°C	21.26		
			T _J =150°C	22.72		



E _{rec}	Reverse Recovery Energy	I _F =200A, -diF/dt=1875A/μs (T _J =150°C), V _R =600V, V _{GE} =-15V	T _J =25°C		2.6	mJ
			T _J =125°C		6.7	
			T _J =150°C		6.9	
R _{θJC}	Diode Thermal Resistance: Junction-to-Case (per Diode)				0.166	°C/W

Module

Symbol	Description	Min.	Typ.	Max.	Units
V _{iso}	Isolation Voltage (All Terminals Shorted)	f=50Hz, 30s		4500	V
T _J	Maximum Junction Temperature			150	°C
T _{JOP}	Maximum Operating Junction Temperature Range	-40		+125	°C
T _{stg}	Storage Temperature	-40		+125	°C
CTI	Comparative Tracking Index	200			
R _{θCS}	Case-to-Sink Thermally (Conductive Grease Applied)			0.03	°C/W
T	Power Terminals Screw:M6	2.5		5.0	N·m
T	Mounting Screw:M6	3.0		6.0	N·m
G	Weight		300		g

Ordering Information Table

Device code	G	T	200	HF	120	T2V	H
	①	②	③	④	⑤	⑥	⑦

- ① - IGBT Module
- ② - Trench, Low Switching Losses IGBT
- ③ - Rated Current (200=200A)
- ④ - Circuit Configuration (Half Bridge)
- ⑤ - Rated Voltage (120=1200V)
- ⑥ - Package Type
- ⑦ - Test Level (Pass the Important Reliability Test-Industrial Grade)

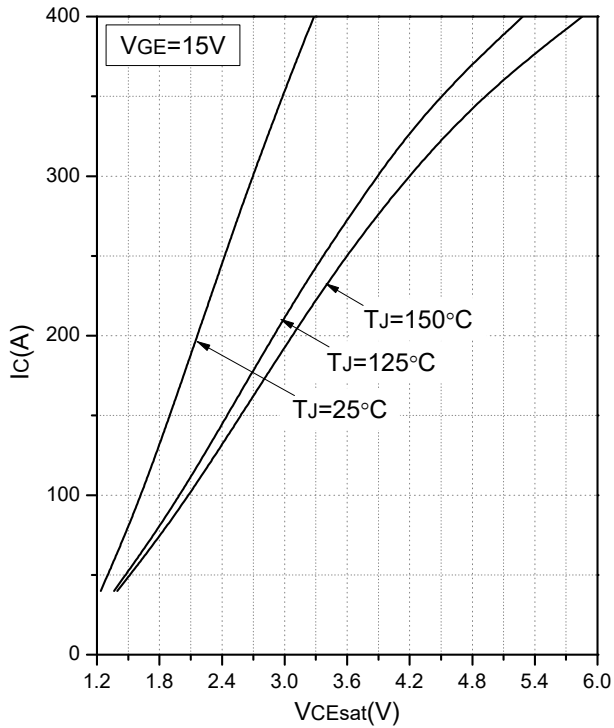


Fig.1 Typical Saturation Voltage Characteristics

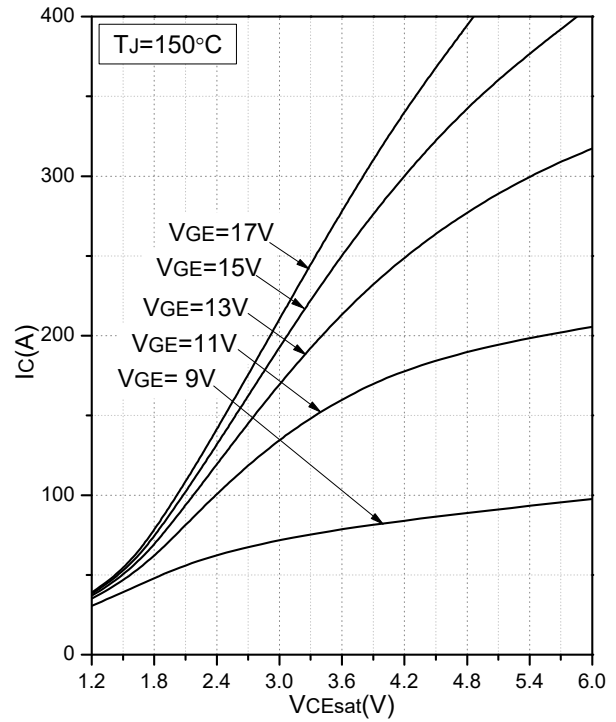


Fig.2 Typical Output Characteristics

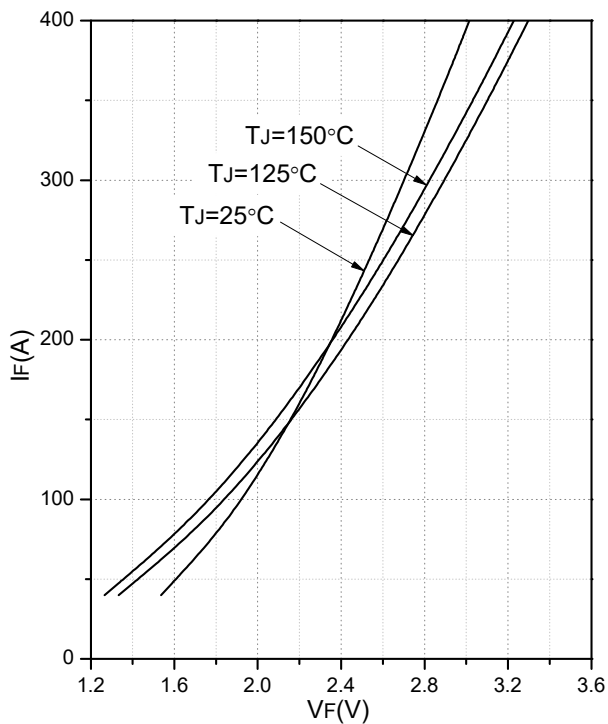


Fig.3 Forward Characteristics of Diode

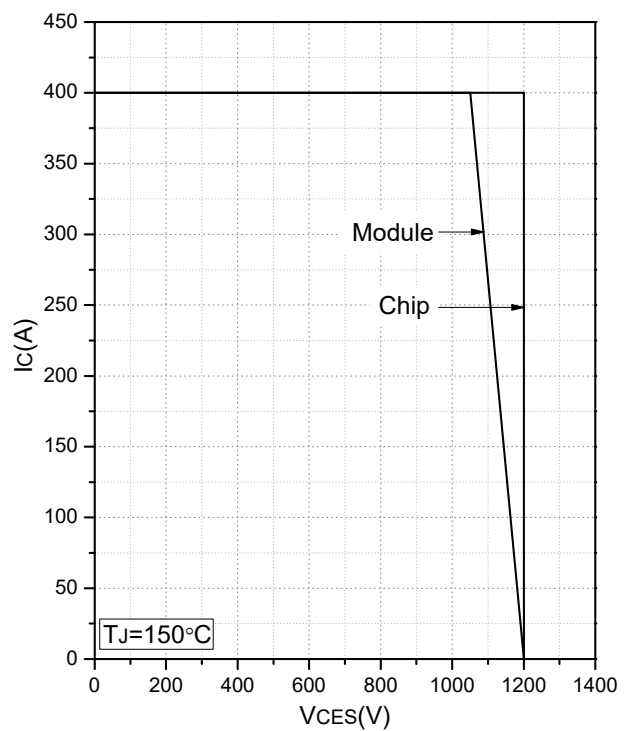


Fig.4 Reverse Bias Safe Operation Area (RBSOA)

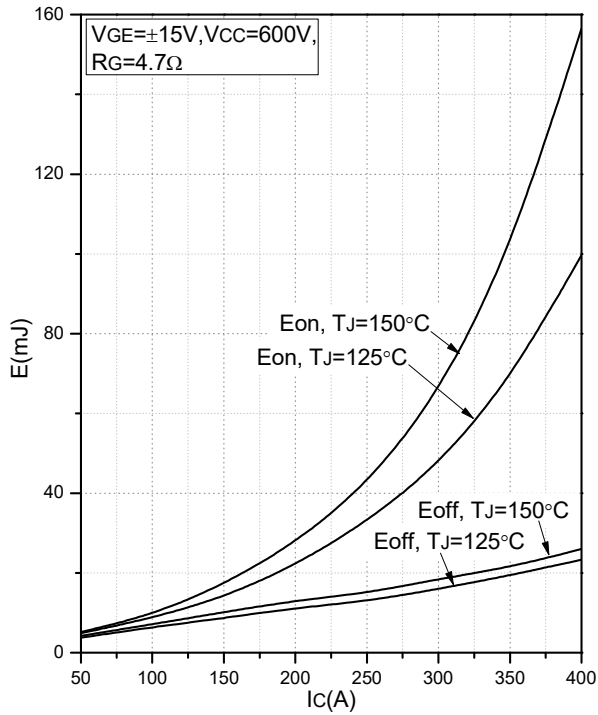


Fig.5 Typical Switching Loss vs. Collector Current

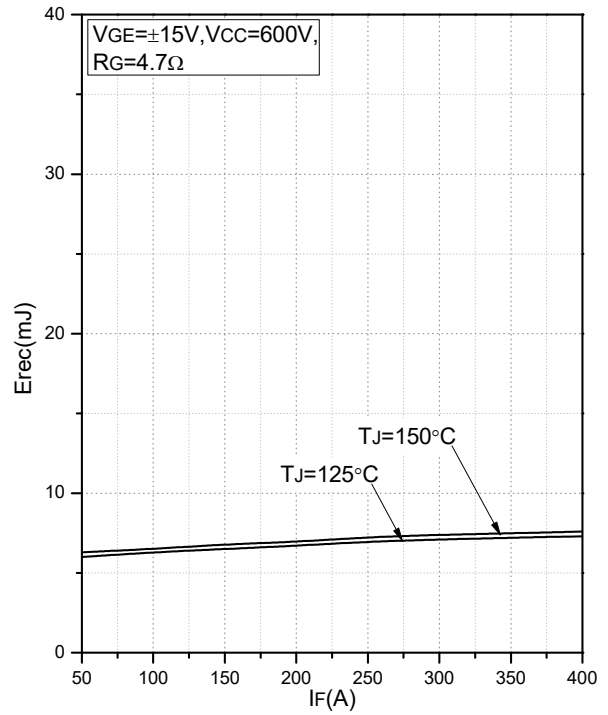


Fig.6 Typical Switching Loss vs. Forward Current

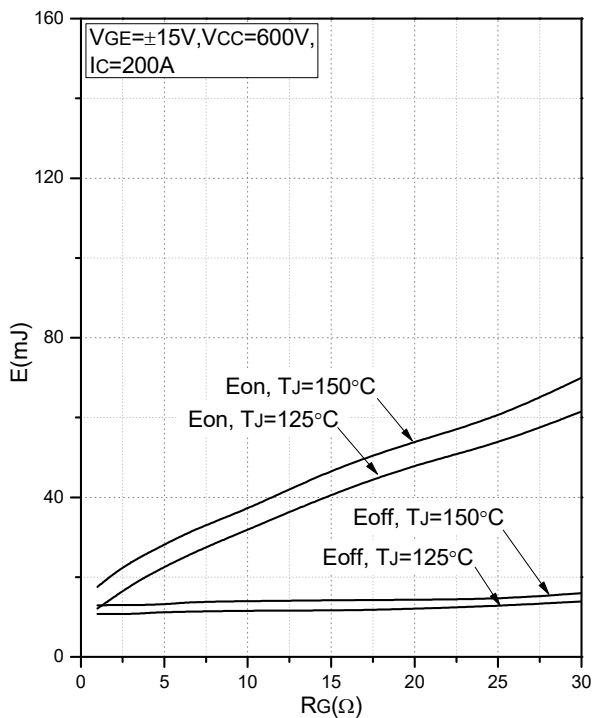


Fig.7 Typical Switching Loss vs. Gate Resistance

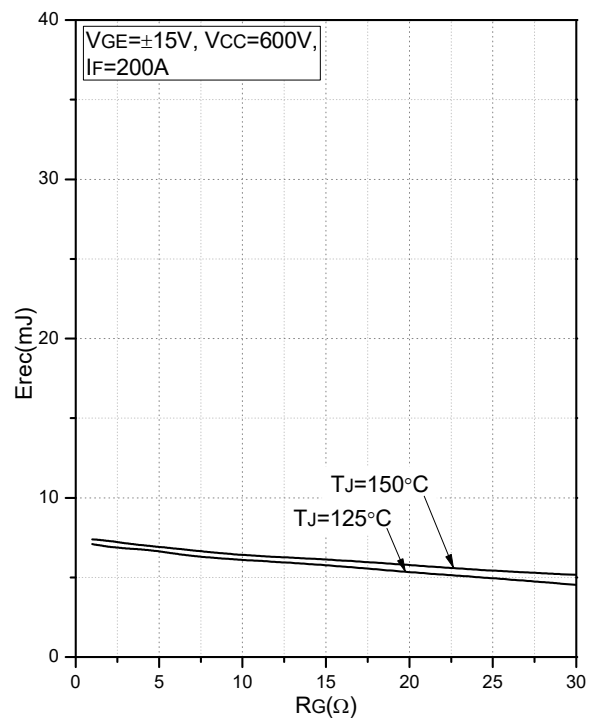


Fig.8 Typical Switching Loss vs. Gate Resistance

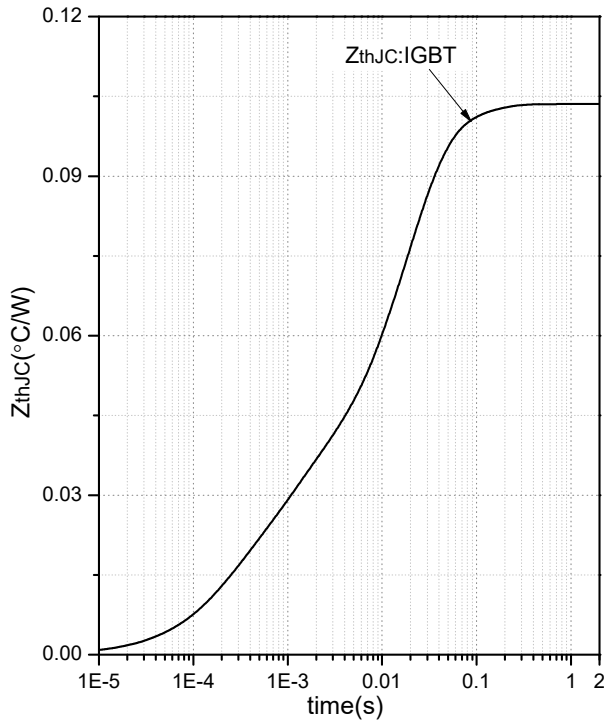


Fig.9 Transient Thermal Impedance (IGBT)

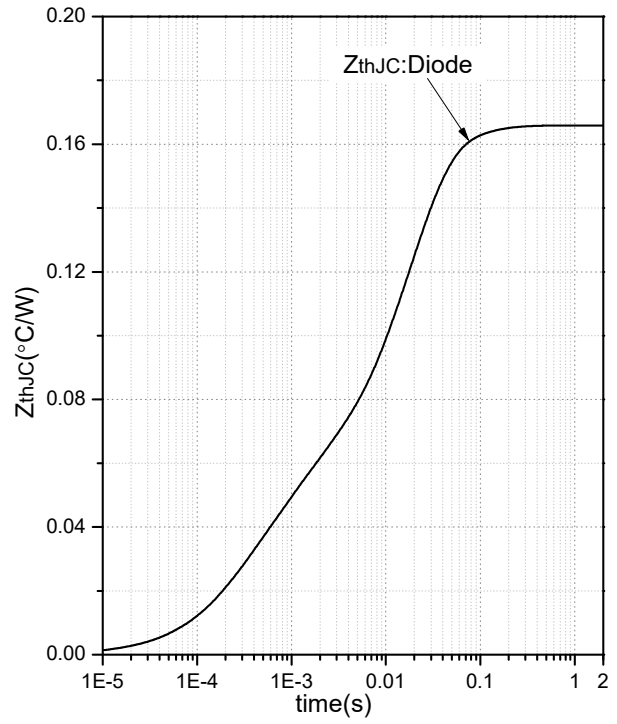


Fig.10 Transient Thermal Impedance (Diode)

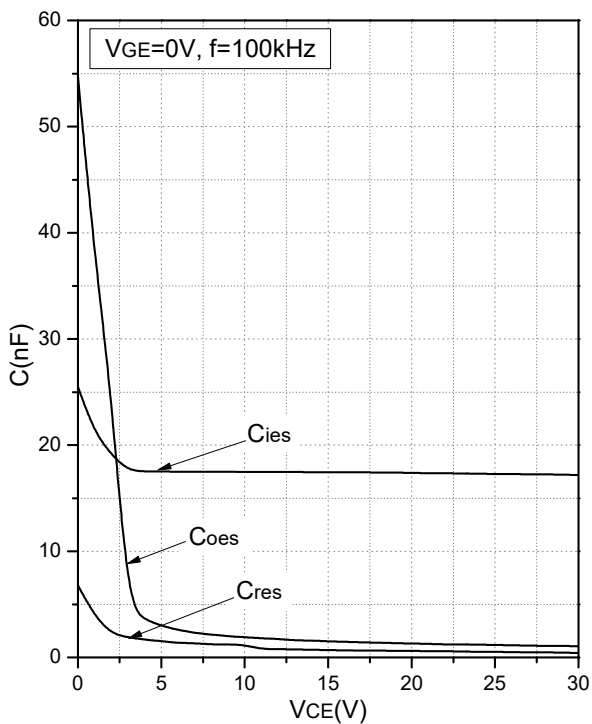
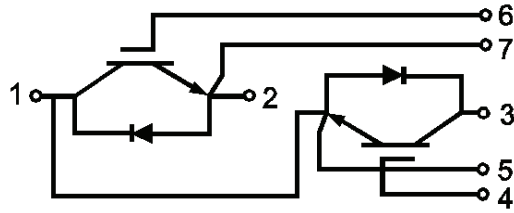


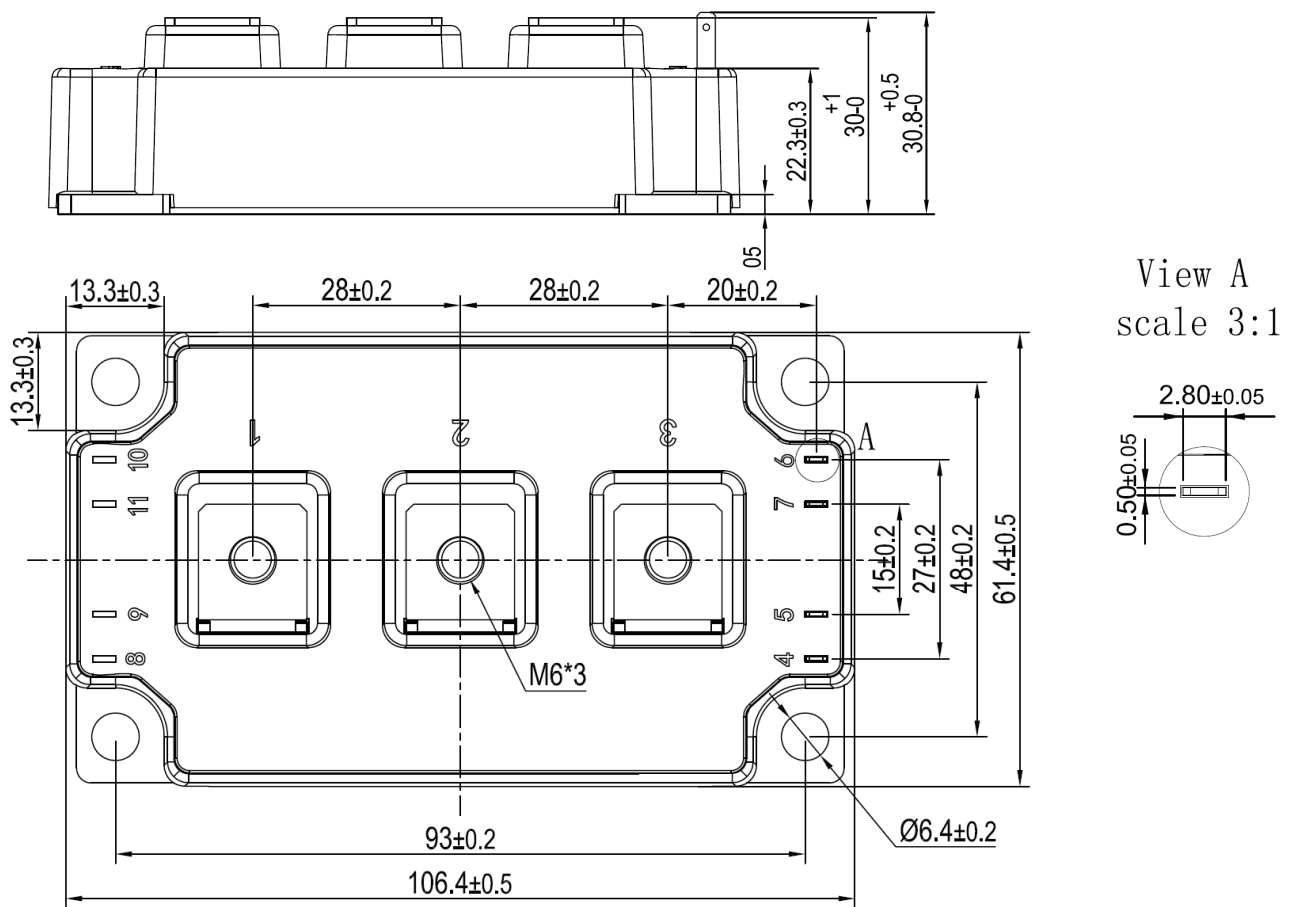
Fig.11 Capacitance Characteristics



Internal Circuit



Package Outline (Unit: mm):





Date	Revision	Notes
09/18/2023	A	Final Version

Announcement

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The released datasheet would be issued with “REV.” + “alphabet characters”.